

Description

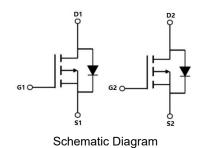
Features

- V_{DS}= -30V, I_D= -5.1A
 - $R_{DS(ON)} < 55 m\Omega$ @ $V_{GS} = -10V$
 - $R_{DS(ON)} < 90 \text{m}\Omega$ @ $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- Lead free product is acquired

Application

- PWM Applications
- Load Switch
- Power Management





Package Marking and Ordering Information

| Device Marking | Device | OUTLINE | Device Package | Reel Size | Reel (PCS) | Per Carton (PCS) |
|----------------|----------|---------|----------------|-----------|---------------|---------------------|
| VSM5DP03-S8 | VSM5DP03 | TAPING | SOP-8 | 13inch | 4000 | 48000 |

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise specified)

| Symbol | Parameter | | Max. | Units |
|-----------------------------------|---|------------------------|-------------|---------------|
| V _{DSS} | Drain-Source Voltage | | -30 | V |
| V _{GSS} | Gate-Source Voltage | | ±20 | V |
| I _D | Continuous Drain Current | T _A = 25℃ | -5.1 | Α |
| | | T _A = 100°C | -3.3 | Α |
| I _{DM} | Pulsed Drain Current note1 | | -20.4 | Α |
| P _D | Power Dissipation | T _A = 25℃ | 2.15 | W |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | | 58 | °C/W |
| T _J , T _{STG} | Operating and Storage Temperature Range | | -55 to +150 | ${\mathbb C}$ |



Electrical Characteristics (T_J=25°C unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Тур. | Max. | Units | | |
|-------------------------|--|---|------|------|-------|-------|--|--|
| Off Characteristic | | | | | | | | |
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D = -250μA | -30 | - | - | V | | |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = -30V, V _{GS} =0V, | - | - | -1 | μΑ | | |
| I _{GSS} | Gate to Body Leakage Current | V _{DS} =0V, V _{GS} = ±20V | - | - | ±100 | nA | | |
| On Charac | On Characteristics | | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | V_{DS} = V_{GS} , I_D = -250 μ A | -1.0 | -1.6 | -2.5 | V | | |
| В | Static Drain-Source on-Resistance | V _{GS} = -10V, I _D = -5A | - | 43 | 55 | mO. | | |
| R _{DS(on)} | note2 | V _{GS} = -4.5V, I _D = -4A | - | 66 | 90 | mΩ | | |
| Dynamic Characteristics | | | | | | | | |
| C _{iss} | Input Capacitance | \\ - 45\\\\ -0\\\ | - | 580 | - | pF | | |
| Coss | Output Capacitance | V _{DS} = -15V, V _{GS} =0V, | - | 98 | - | pF | | |
| C _{rss} | Reverse Transfer Capacitance | f=1.0MHz | - | 74 | - | рF | | |
| Qg | Total Gate Charge | \/ - 15\/ - 5 10 | - | 6.8 | - | nC | | |
| Q _{gs} | Gate-Source Charge | V_{DS} = -15V, I_D = -5.1A, V_{GS} = -10V | - | 1 | - | nC | | |
| Q_{gd} | Gate-Drain("Miller") Charge | VGS10V | - | 1.4 | - | nC | | |
| Switching | Characteristics | | | | | | | |
| t _{d(on)} | Turn-on Delay Time | | - | 14 | - | ns | | |
| t _r | Turn-on Rise Time | V_{DD} = -15V, I_{D} = -1A, | - | 61 | - | ns | | |
| t _{d(off)} | Turn-off Delay Time | V_{GS} = -10V, R_{GEN} =2.5 Ω | _ | 19 | - | ns | | |
| t _f | Turn-off Fall Time | | - | 10 | - | ns | | |
| Drain-Soul | rce Diode Characteristics and Maxii | mum Ratings | | | | | | |
| Is | Maximum Continuous Drain to Source Diode Forward Current | | | - | -5.1 | Α | | |
| I _{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | | - | -20.4 | Α | | |
| V _{SD} | Drain to Source Diode Forward Voltage | V _{GS} =0V, I _S = -5.1A | - | -0.8 | -1.2 | V | | |

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

^{2.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%



Typical Performance Characteristics

Figure1: Output Characteristics

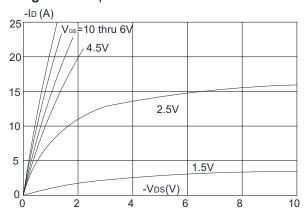


Figure 3:On-resistance vs. Drain Current

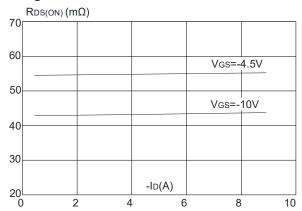


Figure 5: Gate Charge Characteristics

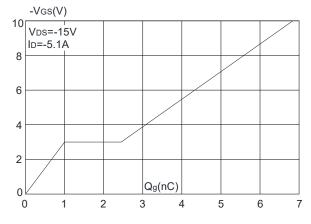


Figure 2: Typical Transfer Characteristics

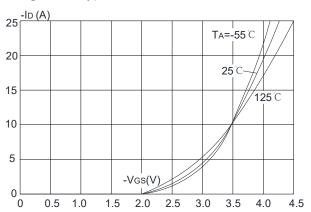


Figure 4: Body Diode Characteristics

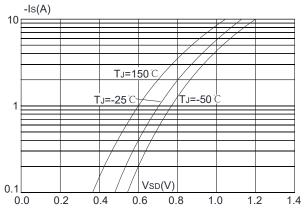


Figure 6: Capacitance Characteristics

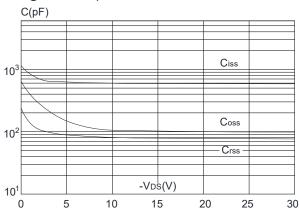




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

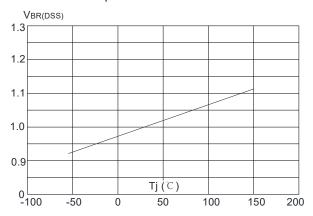


Figure 9: Maximum Safe Operating Area

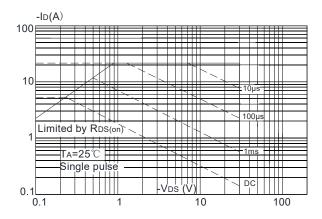


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

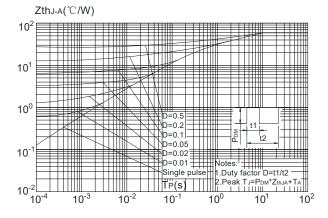


Figure 8: Normalized on Resistance vs. Junction Temperature

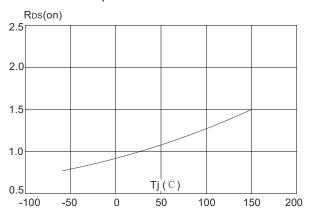
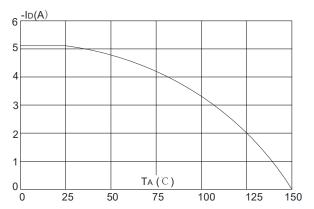


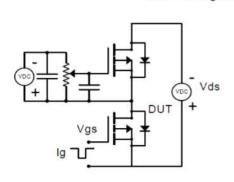
Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

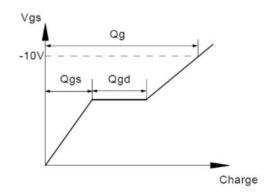




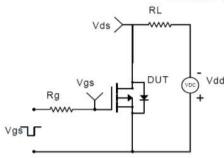
Test Circuit

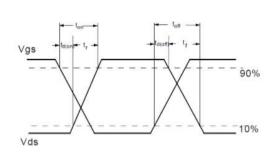
Gate Charge Test Circuit & Waveform



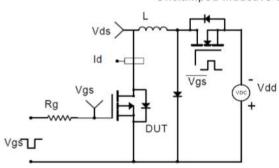


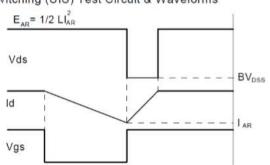
Resistive Switching Test Circuit & Waveforms





Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





Diode Recovery Test Circuit & Waveforms

